

Certificate of RoHS2 Compliance for GPU Computing Systems

Date: 2021, May, 05th

I. RoHS Directive

The Directive 2011/65/EU with amendment 2015/863/EU of the European Parliament and Council of 31 March 2015 on the restrictions of the use of certain hazardous substances in electrical and electronic equipment is hereinafter referred to as the RoHS Directive.

The RoHS Directive bans the placing on the EU market of new Electrical and Electronic Equipment (EEE) containing more than the set levels of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyl (PBB), Polybrominated diphenyl ethers (PBDE) from 1 July 2006 and Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP) from 22 July 2019.

II. Use of RoHS Controlled Substances

PNY Technologies Europe hereby certifies that our products are RoHS compliant while the products listed below under "III. Applicable Products" may contain Lead, Mercury, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE), Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP) with a limit of 1000ppm and Cadmium with a limit of 100ppm defined per homogeneous material.

For purposes of this Certificate the following definitions apply:

- The term homogeneous material means a material that cannot be mechanically disjointed into different materials. The term homogeneous is understood as of uniform composition throughout, so examples of homogeneous materials would be individual types of plastics, ceramics, glass, metals, alloy, paper, board, resins and coatings.
- The term mechanically disjointed means that the materials can be, in principle, separated by mechanical actions such as unscrewing, cutting, crushing, grinding and abrasive processes.

III. Applicable Product(s) (PNY Product Number)

- NVIDIA Tesla M10 *
- NVIDIA Tesla P40 *
- NVIDIA Tesla V100S 32GB*
- NVIDIA T4 *
- NVIDIA A100 *
- NVIDIA A40 *
- NVIDIA A10 CEC *
- NVIDIA A30 *

Exemptions:

For these products lead, Copper alloy, Cadmium (and its compounds) may be used in some electronic components while the application of these substances in such product(s) is exempted from the requirements of Article 4 § 1 (Applications exempted listed in Annex: III) of the RoHS Directive and associated Commission Delegated Directives.

- ☑ 6(a)-I Lead as an alloying element in steel for machining purposes containing up to 0,35 % lead by weight and in batch hot dip galvanised steel components containing up to 0,2 % lead by weight \square 6(b)-I – Lead as an alloying element in aluminum containing up to 0.4% lead by weight, provided it stems from lead-bearing aluminum scrap recycling \square 6(b)-II – Lead as an alloying element in aluminum for machining purposes with a lead content of up to 0.4% lead by weight \square 6(c) – Copper alloy containing up to 4% lead by weight ☑ 7(a) – Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) ☑7(c)-I – Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound □ 7(c)-II –Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher. □ 7(c)-IV – Lead in PZT based dielectric ceramic materials for capacitors which are part of integrated circuits or discrete semiconductors. \square 8(b) (I) – Cadmium and its compounds in electrical contacts used in: - Circuit breakers,
 - Thermal sensing controls,
 - Thermal motor protectors (excluding hermetic thermal motor protectors),
 - AC switches rated at:
 - 6 A and more at 250 V AC and more, or
 - 12 A and more at 125 V AC and more.
 - DC switches rated at 20 A and more at 18 V DC and more, and
 - Switches for use at voltage supply frequency ≥ 200 Hz
- □ 15(a) Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies:
 - A semiconductor technology node of 90 nm or larger;
 - A single die of 300 mm² or larger in any semiconductor technology node;
 - Stacked die packages with die of 300 mm2 or larger, or silicon interposers of 300 mm2 or larger

IV. Important Disclaimer

The information provided herein is to the best of PNY Technologies Europe best knowledge and belief accurate as of the date that it was provided. PNY Technologies Europe bases such knowledge and belief on information provided by third parties, and PNY Technologies Europe makes no representation or warranty as to the accuracy of such third party information. PNY Technologies Europe has taken, and continues to take, reasonable steps to provide representative and accurate information to its customers, but may have not conducted destructive testing or chemical analysis on incoming materials and chemicals. Certain PNY Technologies Europe suppliers consider material content to be confidential information and

thereby proprietary, whereby such information may not be available for release to customers. Neither PNY Technologies Europe nor any of its affiliates shall be liable for loss of use, revenue, profit, or for any special, incidental, or consequential damages arising out of, connected with, or resulting from the information provided in this Certificate, or otherwise; and in no event shall PNY Technologies Europe's or any of its affiliates' direct liability arising out of, connected with, or resulting from such information exceed the purchase price of the product(s) referenced in this Certificate.

This Certificate is intended only for the use of the company to which it is addressed and no other person or entity is entitled to rely on it.

V. Important Legal Note

The information contained herein is intended to assist those using PNY Technologies Europe EEEs in complying with the RoHS Directive. Certain of the information contained herein is simplified guidance based on complex and changing legislation, and does not constitute legal advice. The RoHS Directive should always be read and understood (as they constitute the law), in contrast with the information contained herein, which is intended to be informative but has no legal authority. You should refer to the RoHS Directive for a full statement of the legal requirements and in the case of any doubt take the independent advice, including your own legal advice. The RoHS Directive may be revised from time to time, so users should take care to keep themselves informed.

VI. Certification

The undersigned hereby certifies that he or she is authorized to sign this Certificate and affirms that all the information provided in this Certificate is true and correct as of the date hereof.

Stéphanie Burtin - Quality Department **PNY Technologies Europe**